

10

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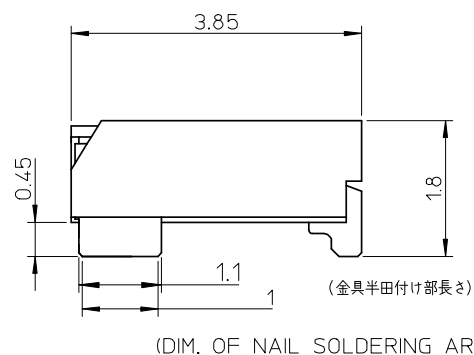
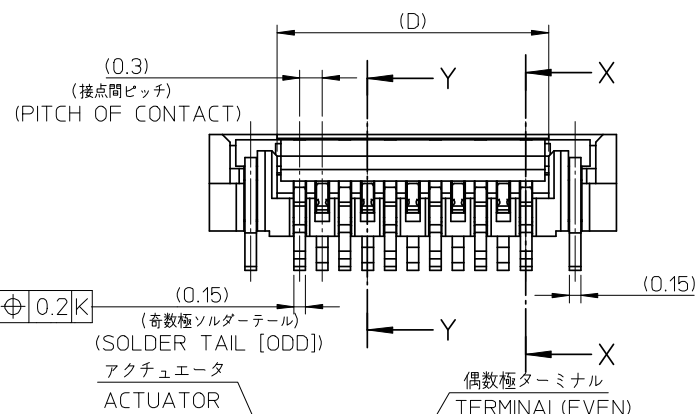
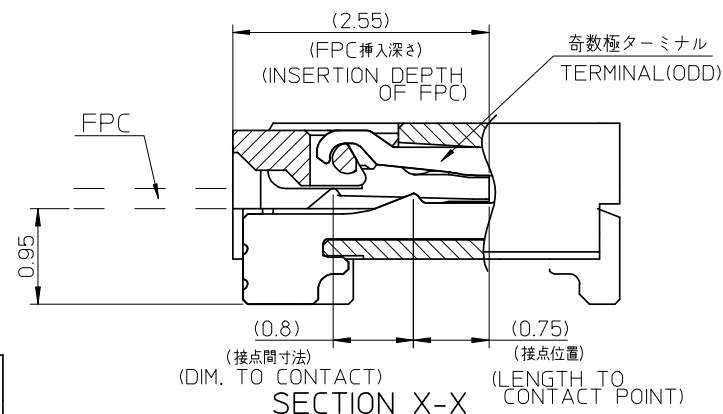
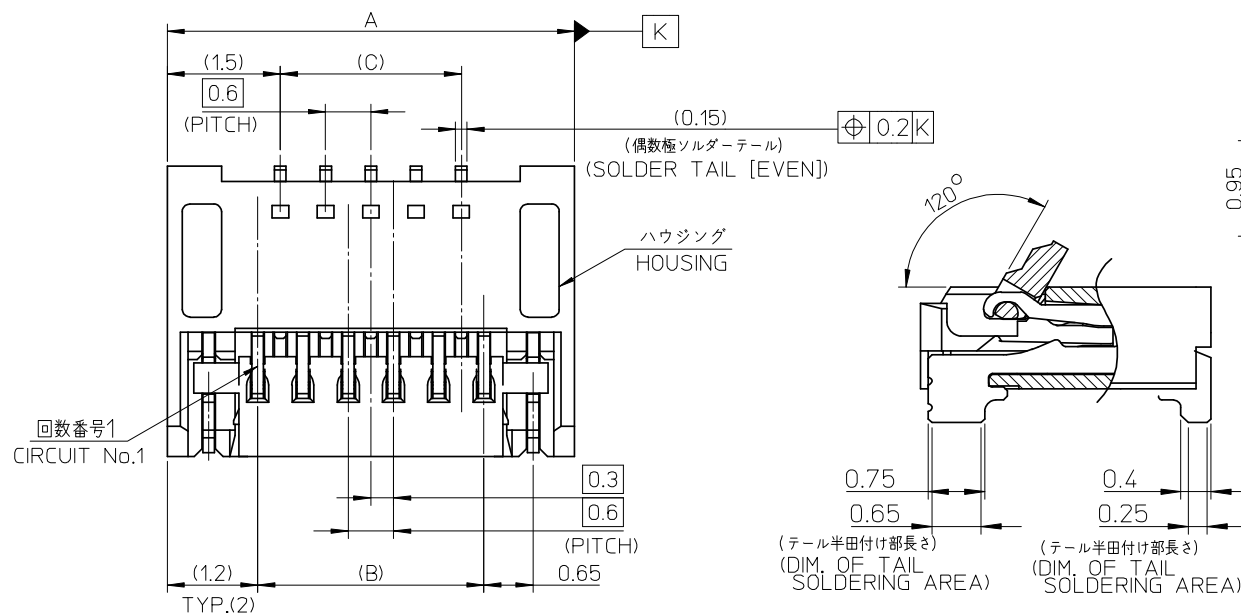
5

4

3

2

1



15.6	14.4	15.0	17.4	501912-5190	501912-5110	51
14.4	13.2	13.8	16.2	501912-4790	501912-4710	47
13.8	12.6	13.2	15.6	501912-4590	501912-4510	45
12.6	11.4	12.0	14.4	501912-4190	501912-4110	41
12.0	10.8	11.4	13.8	501912-3990	501912-3910	39
11.4	10.2	10.8	13.2	501912-3790	501912-3710	37
10.8	9.6	10.2	12.6	501912-3590	501912-3510	35
10.2	9.0	9.6	12.0	501912-3390	501912-3310	33
8.4	7.2	7.8	10.2	501912-2790	501912-2710	27
7.8	6.6	7.2	9.6	501912-2590	501912-2510	25
7.2	6.0	6.6	9.0	501912-2390	501912-2310	23
6.6	5.4	6.0	8.4	501912-2190	501912-2110	21
4.8	3.6	4.2	6.6	501912-1590	501912-1510	15
D	C	B	A	EMBOSS-TAPE PKG ORDER No.	MATERIAL No.	CIRCUIT

MODEL No. 501912-**10

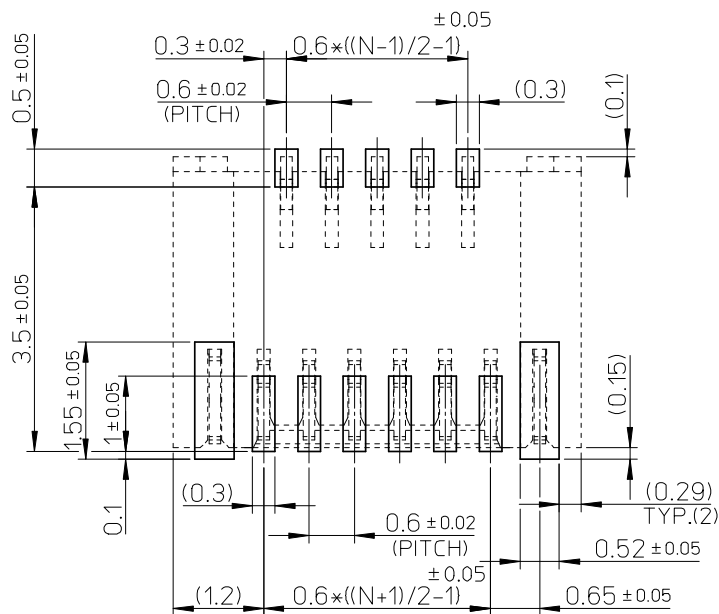
0.3 FPC CONN E/O HSG
ASSY (HGT=1.8MM)
GOLDPLATING

MOLEX INCORPORATED

DOCUMENT NO.
SD-501912-001

SHEET NO.
1 OF 2

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION



参考基板レイアウト図
(マウント面)
(MOUNTING SIDE)

注記 NOTES

1. 使用材料 MATFRIAL

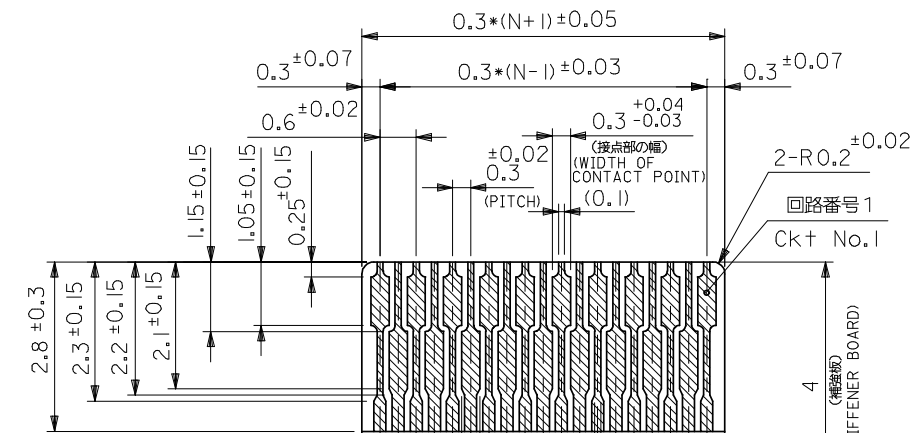
ハウジング : 耐熱性樹脂 ガラス充填 UL94V-0
HOUSING : HEAT RESISTANCE POLYMER (GLASS FILLED) UL94V-0
アクチュエータ : 耐熱性樹脂 ガラス充填 UL94V-0
ACTUATOR : HEAT RESISTANCE POLYMER (GLASS FILLED) UL94V-0
ターミナル : 銅合金 (t=0.15), ニッケル下地金メッキ
TERMINAL : COPPER ALLOY, GOLD OVER NICKEL PLATING.
金具 : 銅合金 (t=0.15), ニッケル下地スズメッキ
FITTING NAIL : COPPER ALLOY , TIN OVER NICKEL PLATING.

ハウジングに黒点がある場合が有りますが、問題はありません。

2. ソルダータール半田付け面、及び金具半田付け面の平坦度 : 0.1mm MAXIMUM.

COPLANARITY OF SOLDER TAILS AND FITTING NAILS
TO BE 0.1mm MAXIMUM.

3. ELV AND RoHS COMPLIANT.



適合FPC推奨寸法
APPLICABLE FPC
RECOMMENDED DIMENSION
(仕上がり厚さ : 0.2 ± 0.03)
(THICKNESS: 0.2 ± 0.03)

FPCについて :

打抜き方向は導体側から補強板側を推奨いたします。
導体部については軟銅箔35マイクロメートルまたは50マイクロメートルを
推奨致します。
補強フィルム材質はポリイミドを推奨します。
接着剤は熱硬化接着剤を推奨します。

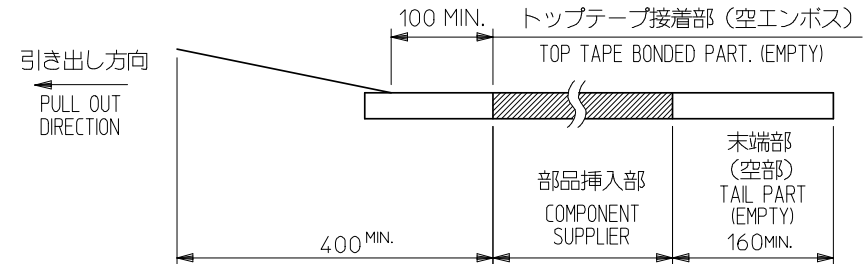
ABOUT FPC

RECOMMENDED PUNCHER DIRECTION : FROM CONDUCTOR SIDE TO STIFFENER FILM SIDE.
RECOMMENDED CONDUCTOR SPEC :
THICKNESS OF SOFT COPPER FOIL : 35 MICROMETER OR 50 MICROMETER
RECOMMENDED MATERIAL :
STIFFENER FILM : POLYIMIDE
BONDING AGENT : THERMOSETTING BONDING AGENT

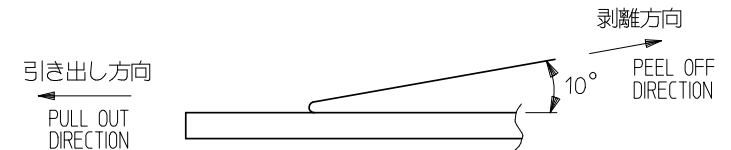
REVISED	EC NO. J2008-3324	DRAWN:HTAGAMI 2008/03/25	CHKD:K.TAKAHASHI 2008/04/07	APPR:K.TAKAHASHI 2008/04/07	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ----	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
						10 UNDER	± 0.2	DRAWN BY M.HAYASHI	DATE 2005/07/28	TITLE 0.3 FPC CONN E/O HSG ASSY (HGT=1.8MM) GOLDPLATING			
						10 OVER 30 UNDER	± 0.25	CHECKED BY H.HIRATA	DATE 2005/07/28				
						30 OVER	± 0.3	APPROVED BY M.SASAO	DATE 2005/07/28	MOLEX INCORPORATED			
						ANGULAR ±3 °		MATERIAL NO.					
						DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE SHEET 1		SD-501912-001		2 OF 2	
								SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			

NOTES

- 製品詳細寸法は製品単体図面を参照して下さい。
FOR DETAIL OF CONNECTOR DIMENSIONS,PLEASE SEE THE DRAWING OF CONNECTOR ITSELF(NOT PACKAGED).
- 梱包数量：3000個／リール
NUMBER OF CONNECTORS：3000PCS/REEL
- リードテープ長さ LEAD TAPE LENGTH



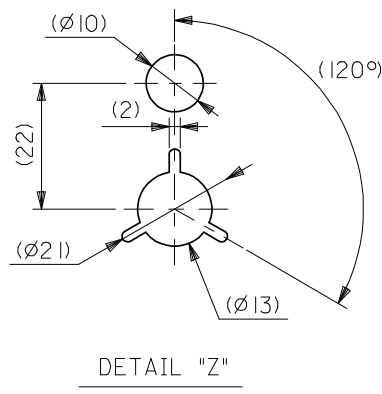
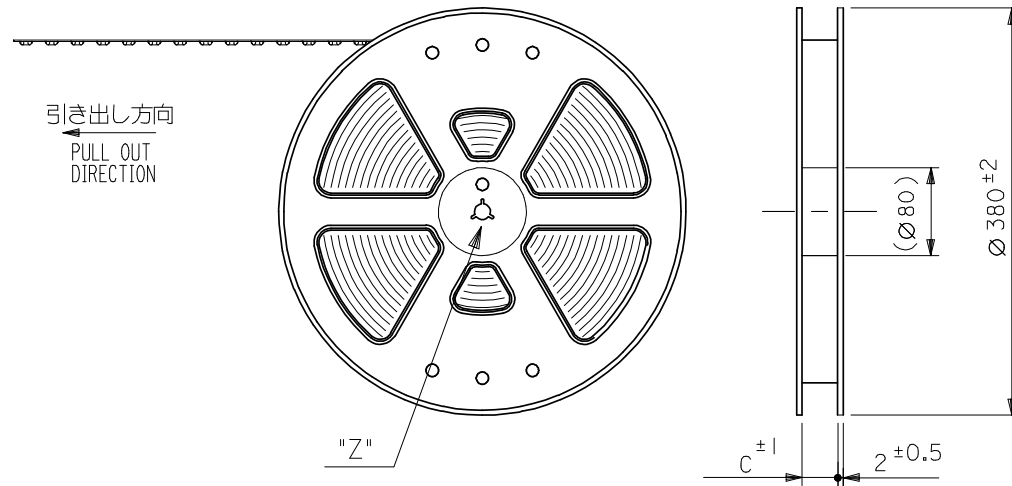
- トップテープの剥離強度：60±35gf (0.25N～0.93N) (剥離方向は下図参照) 尚、本規格値は出荷時に適用。(但し、輸送時に剥離が発生しないこと。)
PEELING OFF FORCE OF TOP TAPE：65gf±30gf (0.25N～0.93N) (PEELING DIRECTION AS SHOWN IN FOLLOWING FIG.) THIS REQUIREMENT SHOULD BE APPLIED AT SHIPMENT. PEEL OFF SHOULD NOT BE ALLOWED , DURING TRANSPORTATION.



5. 材料(MATERIAL)

キャリアテープ (CARRIER TAPE)：ポリスチレン (POLYSTYREN)
トップテープ (TOP TAPE)：PET, PE, PEF
リール(REEL)：ポリスチレン(PS) <リサイクル材を含む>
POLYSTYREN(PS) <RECYCLE MATERIAL CONTAINED>

- C寸法は SHEET 2～4を参照下さい。
SEE SHEET 2～4(DIMENSION C).
- ELV AND RoHS COMPLIANT.



REVISED EC NO: J2008-3324 DRAWN: HTAGAMI CHKD: K TAKAHASHI APPR: K TAKAHASHI	DESCRIPTION REV	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	501912-**-90 DESIGN UNITS METRIC	 THIRD ANGLE PROJECTION	MODEL NO.	
		10 UNDER	± 0.2	DRAWN BY M. HAYASHI	DATE 2005/10/11	TITLE EMBSTP PKG FOR 0.3 FPC CONN (HGT=1.8MM) GOLD PLATING	 MOLEX INCORPORATED	SHEET NO. 1 OF 4	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION	
		10 OVER 30 UNDER	± 0.25	CHECKED BY H. HIRATA	DATE 2005/10/11					
		30 OVER	± 0.3	APPROVED BY M. SASAO	DATE 2005/10/11					
		ANGULAR ±3 °		MATERIAL NO.		DOCUMENT NO. SD-501912-002				
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE						
				SIZE A3						

10 9 8 7 6 5 4 3 2 1

F

E

D

C

B

A

F

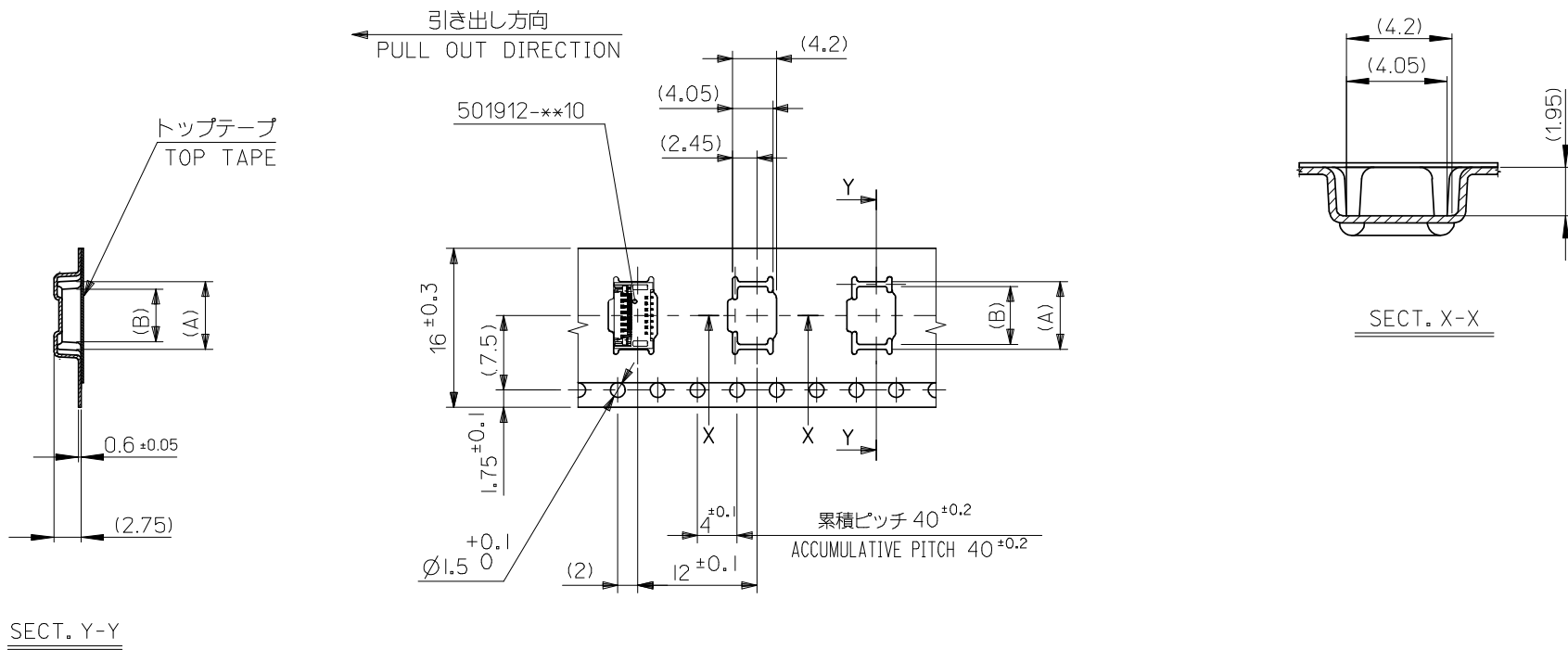
E

D

C

B

A



16 mm幅キャリアテープ
16mm WIDTH CARRIER TAPE

16	17.5	4.6	6.8	501912-1590	15
キャリアテープ幅 CARRIER TAPE WIDTH	C	(B)	(A)	製品番号 MATERIAL No.	極数 CK+
				501912-**-90	MODEL No.

REVISED EC NO: J2008-3324 DRAWN: HTAGAMI 2008/03/25 CHKD: KITAKAHASHI 2008/04/07 APPR: KITAKAHASHI 2008/04/07	DESCRIPTION REV	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		10 UNDER	± 0.2	DRAWN BY M. HAYASHI	DATE 2005/10/11	TITLE EMBSTP PKG FOR 0.3 FPC CONN (HGT=1.8MM) GOLD PLATING				
		10 OVER 30 UNDER	± 0.25	CHECKED BY H. HIRATA	DATE 2005/10/11					
		30 OVER	± 0.3	APPROVED BY M. SASAO	DATE 2005/10/11	MOLEX INCORPORATED				
		ANGULAR ±3 °		MATERIAL NO.		DOCUMENT NO.		SHEET NO.		
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE		SD-501912-002		2 OF 4		
				THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION						

